

AMENDMENTS TO THE CLAIMS:

1.-5. (Canceled)

6. (Currently amended) A semiconductor device in accordance with claim 1 comprising:
a semiconductor chip having a plurality of electrodes formed on the surface thereof;
an interposer substrate on which said semiconductor chip is mounted;
a core substrate constituting the base of said interposer substrate;
built-up layers built on only one surface of said core substrate; and
an anisotropic conductive layer which is formed on the other surface of said core substrate, and
via which said semiconductor chip is mounted on said core substrate;
wherein the electrodes on said core substrate and those on said semiconductor chip being
electrically connected via said anisotropic conductive layer; and
wherein, on the core substrate surface on which said built-up layers are built, reinforced patterns are formed at the positions corresponding to the electrodes on said semiconductor chip.

7. (Currently amended) A The semiconductor device in accordance with claim 6, wherein said interposer substrate is constructed by forming built-up layers on said core substrate, wherein electrodes are each formed so as to be continuous with a conductive portion which passes through said built-up layer layers, and wherein said electrodes are connected to the motherboard to be affixed thereon.

8. (Currently amended) A The semiconductor device in accordance with claim 7, wherein, on the outer surface of said built-up layer layers, no wiring patterns exist at the positions corresponding to said reinforced patterns, and wherein through-holes are formed at the corresponding positions on the motherboard to mount said semiconductor device.

9.-11. (Withdrawn)